

Remarks

Status of Claims

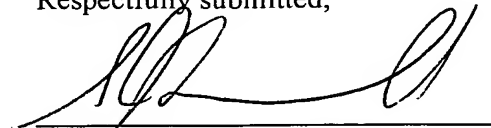
The claims have been amended to clarify that the palladium layer is added to the interface portion to render it a solderable interface portion. Support for this can be found throughout the application, including, for example, a portion of Claim 8.

Examiner Interview

Applicants wish to thank the Examiner for participating in an interview on July 18, 2006. In the interview, the Examiner made clear that adding the palladium layer to the tungsten layer did not necessarily distinguish the claimed invention over the prior art. The Applicants suggested adding language to make clear that the palladium layer was added to the interface portion at the interface portion would therefore be solderable. The Examiner acknowledged that this would overcome the rejection as it currently stands, but indicated that an additional search would be required.

An early and favorable response is respectfully submitted.

Respectfully submitted,



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